



## Material Content Data Sheet



Halogen-Free

**Sales Product Name** ISC08XN10NM6

**Issued**

07. February 2022

**MA#** MA005410418

**Package** PG-TDSON-8-37

**Weight\***

114.41 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.734	0.64	0.64	6415	6415
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	iron	7439-89-6	0.049	0.04		427	
	non noble metal	copper	7440-50-8	48.769	42.64	42.69	426275	426830
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	398	398
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		736	
	plastics	epoxy resin	-	6.651	5.81		58137	
	inorganic material	silicondioxide	60676-86-0	35.361	30.91	36.79	309082	367955
leadfinish	non noble metal	tin	7440-31-5	1.392	1.22	1.22	12163	12163
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1694	1694
solder	non noble metal	tin	7440-31-5	0.020	0.02		172	
	noble metal	silver	7440-22-4	0.025	0.02		215	
	non noble metal	lead	7439-92-1	0.940	0.82	0.86	8217	8604
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	non noble metal	copper	7440-50-8	17.131	14.97	14.99	149740	149935
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.60	2.60	25972	26006
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com